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### Dimensions

Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
T	1.25mm +/-0.15mm
S	0.75mm MIN
B	0.5mm +/-0.25mm

### Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	2500

### General Information

Series	SMD Indust COG HVHT200C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable, Low Loss
Features	High Temp, Ultra-Stable, Low Loss
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	14 mg
Shelf Life	78 Weeks
MSL	1

### Specifications

Capacitance	47 pF
Measurement Condition	1MHz 1.0Vrms
Capacitance Tolerance	1%
Voltage DC	500 VDC
Dielectric Withstanding Voltage	750 VDC
Temperature Range	-55/+200°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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